



NORYL™ Resin SA90

Americas: COMMERCIAL

NORYL SA90 resin is a modified low molecular weight resin with increased hydroxyl functionality. It is designed specifically for use as a reactive component in epoxy and cyanate ester thermosets in electronic, coatings, adhesives, and composites applications. It has outstanding solubility in toluene & methyl ethyl ketone (MEK) and a low solution viscosity. Targeted application areas are in enhancing the performance (e.g. thermal, dielectric, mechanical, flame retardancy, and moisture uptake properties) of epoxy resins used in electronic packaging which include PCB laminates, copper clad laminates, epoxy prepregs, and protective coatings as well as various other composites applications.

TYPICAL PROPERTIES ¹	TYPICAL VALUE	Unit	Standard
THERMAL			
Tg (half width)	140	°C	SABIC Method
PHYSICAL			
Specific Gravity	1.02	-	ASTM D 792
Physical Form	PELLET	-	SABIC Method
Intrinsic Viscosity	0.09	dl/g	SABIC Method
Phenolic End-group Content	21500	ppm	SABIC Method
Hydroxy Equivalent Weight (HEW)	840	g/mol	SABIC Method
Solubility, Toluene (21°C)	50	wt%	SABIC Method
Solubility, Methyl Ethyl Ketone (21°C)	50	wt%	SABIC Method
Mn	1600	-	SABIC Method
Viscosity, 50 wt% in toluene, 25°C	298	cP	SABIC Method
Viscosity, 50 wt% in methyl ethyl ketone, 25°C	160	cP	SABIC Method
ELECTRICAL			
Dielectric Constant, 1 MHz	2.54	-	ASTM D 150
Dissipation Factor, 1 MHz	0.0007	-	ASTM D 150